ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TJDA-01292
REV: E1
SUN REV: Not In VersionControl

LAYER NAME = Bottom Solder
TID #: TJDA-01292

PLOT NAME = Bottom Solder Mask
GENERATED: 7/31/2017 1:50:04 PM
TEXAS INSTRUMENTS
DRILL TABLE

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Hit Count</th>
<th>Finished Hole Size</th>
<th>Plated</th>
<th>Hole Type</th>
</tr>
</thead>
<tbody>
<tr>
<td>981D</td>
<td></td>
<td>12.00mil (0.3048mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td>80</td>
<td></td>
<td>58.07mil (1.4750mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td>16</td>
<td></td>
<td>86.61mil (2.2000mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td>12</td>
<td></td>
<td>33.46mil (0.8500mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td>10</td>
<td></td>
<td>10.00mil (0.0160mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
</tbody>
</table>

4028 Total

FOR PTH +3/-3MIL
FOR 12MIL DRILL +0/-12MIL
Copper thickness is 2oz.
This is not an impedance control board.
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